

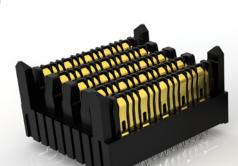
# HIGH-SPEED BACKPLANE SYSTEMS

# **HIGH-DENSITY • DESIGN FLEXIBILITY • HIGH RELIABILITY**

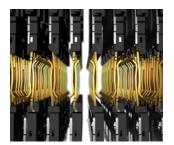


# EXAMAX® HIGH-SPEED BACKPLANE

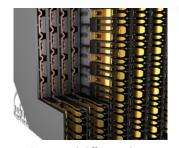
- Meets industry specifications such as PCI Express<sup>®</sup>, Intel OPI and VPI, SAS, SATA, Fibre Channel, InfiniBand™ and Ethernet
- Exceeds OIF CEI-28G-LR specification for 28 Gbps standards
- 24 72 pair designs (4 and 6 pairs;
  6, 8, 10 and 12 columns)
- Wafer design increases isolation for reduced crosstalk
- Press-fit tails provide a reliable electrical connection
- Cable assemblies available (EBCM/EBCF)







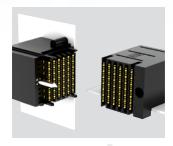
Two reliable points of contact



Staggered differential pair design with an embossed ground plane



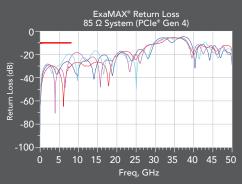
Coplanar available to bypass the midplane (EBTM-RA)



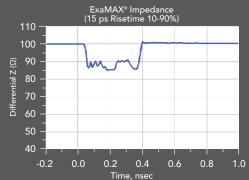
Direct-mate orthogonal (EBDM-RA) eliminates the midplane for a shorter signal path

## **PERFORMANCE CHARTS**

ExaMAX® is engineered for 92  $\Omega$  impedance to address both 85  $\Omega$  and 100  $\Omega$  applications







ExaMAX® is a trademark of AFCI

# XCEDE® HD HIGH-DENSITY BACKPLANE

- Small form factor and modular design provides significant space-savings and flexibility
- High-performance system
- Up to 84 differential pairs per linear inch
- 3, 4 and 6-pair designs on 4, 6 and 8 columns
- Integrated power, guidance, keying and side walls available
- 85  $\Omega$  and 100  $\Omega$  options
- Combine any configuration of modules to create one integrated receptacle (BSP Series); corresponding terminal modules are individually mounted to the backplane



#### HDTM/HDTF



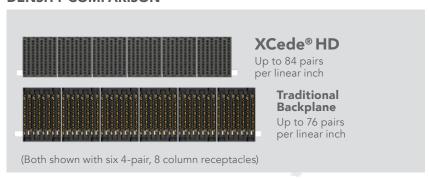




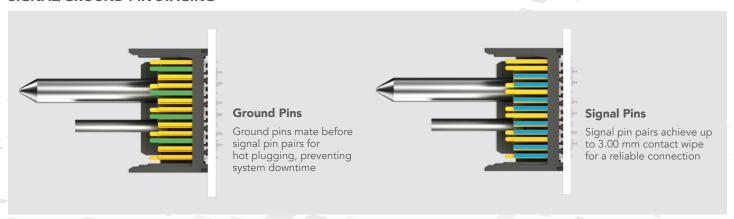
#### **SMALL FORM FACTOR**



#### **DENSITY COMPARISON**



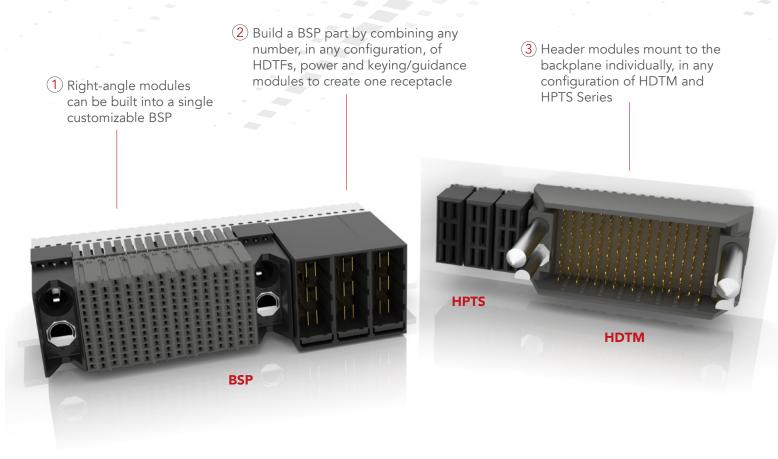
#### SIGNAL/GROUND PIN STAGING



## **MODULAR DESIGN**

XCede® HD consists of signal, power and keying/guidance modules for incredible design flexibility. The modules can be customized in any configuration to meet specific application requirements. Contact HSBP@samtec.com for more information about building a full XCede® HD solution.

## How to build a full solution:



XCede® is a registered trademark of Amphenol Corporation.



# **EXAMAX® BACKPLANE CABLE ASSEMBLIES**

- Utilizes Samtec's Eye Speed® ultra low skew twinax cable technology for improved signal integrity, increased flexibility and routability
- Highly customizable with modular flexibility
- Reduce costs due to lower layer counts
- 30 and 34 AWG
- Multiple end options available





**EBCF** 

EBTM/EBCL

## **DESIGN FLEXIBILITY**



4 and 6 pairs; 4-16 columns



Intermateable with all ExaMAX® connectors



Integrated guidance and keying options

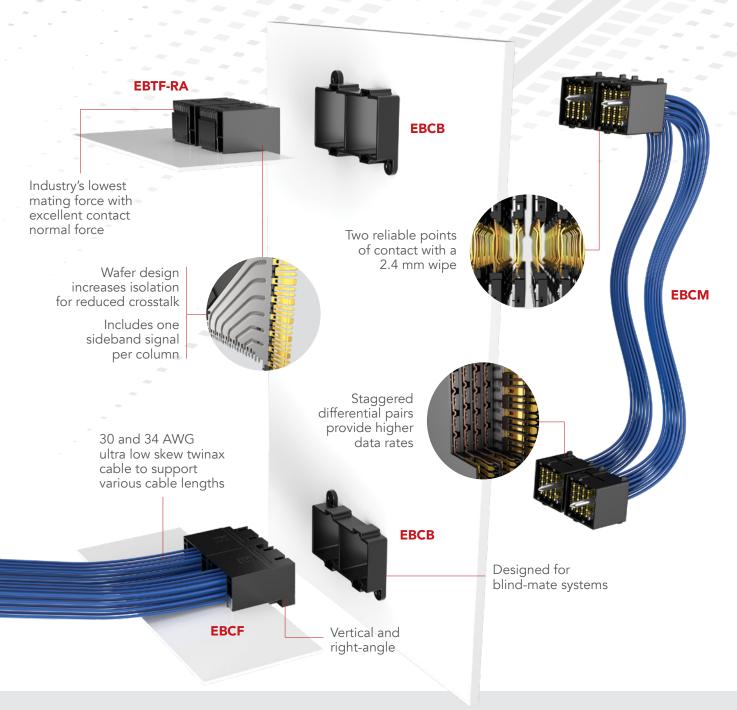


Cable-to-DMO (Direct Mate Orthogonal)

#### HIGH-DENSITY APPLICATION



Increases architectural flexibility by overcoming the limitations of a traditional connector-to-connector backplane

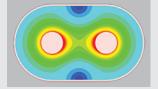


## **ULTRA LOW SKEW TWINAX CABLE**

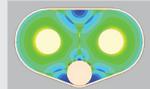
Samtec's Eye Speed® co-extruded twinax cable technology eliminates the performance limitations and inconsistencies of individually extruded dielectric twinax cabling, improving signal integrity, bandwidth and reach for high-performance system architectures.

- Tight coupling between signal conductors
- Improved bandwidth and reach
- Improved signal integrity and eye pattern opening





✓ Good design coupling with Samtec's co-extruded ultra low skew twinax



➤ Bad design coupling with individually extruded conductors & drain wire



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samtec.com/backplane